



Materials Declaration Form


IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2021-06-04
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M95M04-DWDW4TP/V	PT6P*9TM41VL	A	Shenzhen	2021-06-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Copper Alloy	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
TSSOP	3x4.4x1	8	L Bend	
Comment	Package : 6P TSSOP 8 BODY 4.4 PITCH 0.65 0079397			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PT6P*9TM41VL				7024499.0	1000015.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	3.635	mg	supplier	die	Silicon (Si)	7440-21-3		3.488	mg	959560	102588
				supplier	metallization	Aluminium (Al)	7429-90-5		0.013	mg	3576	382
				supplier	metallization	Copper (Cu)	7440-50-8		0.043	mg	11829	1265
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.005	mg	1376	147
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1651	176
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	3026	324
Lead-frame	M-011 Other inorganic materials	14.517	mg	supplier	alloy	Copper (Cu)	7440-50-8		14.147	mg	974500	416079
				supplier	alloy	Iron (Fe)	7439-89-6		0.341	mg	23460	10017
				supplier	alloy	Zinc (Zn)	7440-66-6		0.017	mg	1200	512
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	840	359
Lead-frame Coating	M-011 Other inorganic materials	0.098	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.090	mg	916800	2655
				supplier	coating	Palladium (Pd)	7440-05-3		0.006	mg	58700	170
				supplier	coating	Gold (Au)	7440-57-5		0.002	mg	24500	71
Die Attach	M-011 Other inorganic materials	0.513	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.411	mg	800000	12079
				supplier	glue or soft solder	2,6-Diglycidylphenyl allyl ether	13561-08-5		0.077	mg	150000	2265
				supplier	glue or soft solder	1,4-bis (2,3-epoxypropoxy) butane	2425-79-8		0.010	mg	20000	302
				supplier	glue or soft solder	Polyoxypropylenediamine	9046-10-0		0.015	mg	30000	453
Wires	M-011 Other inorganic materials	0.039	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.039	mg	1000000	1160
Encapsulation	M-011 Other inorganic materials	15.196	mg	supplier	Moulding Compound	Epoxy Resin	Proprietary		1.276	mg	83951	37522
				supplier	Moulding Compound	Phenol Resin	Proprietary		0.851	mg	55967	25015
				supplier	Moulding Compound	Silicon Dioxide	60676-86-0		12.917	mg	850007	379912
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.085	mg	5597	2501
				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.068	mg	4477	2001
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	916800	27
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	2
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	1

